

Title (en)

SOLDERING METHOD FOR JOINING DIFFERENT BASIC METALLIC MATERIALS BY MEANS OF AN EXOTHERMAL REACTION, AND HEAT EXCHANGER PRODUCED ACCORDING TO SAID METHOD

Title (de)

LÖTVERFAHREN ZUM VERBINDEN VERSCHIEDENER METALLISCHER GRUNDWERKSTOFFE DURCH EINE EXOTHERME REAKTION, SOWIE EIN MIT DEM VERFAHREN HERSTELLBARER WÄRMETAUSCHER

Title (fr)

PROCEDE DE SOUDAGE DESTINE A LA CONNEXION DE DIVERS MATERIAUX METALLIQUES DE BASE PAR REACTION EXOTHERMIQUE ET ECHANGEUR THERMIQUE POUVANT ETRE FABRIQUE AU MOYEN DE CE PROCEDE

Publication

EP 1951468 A1 20080806 (DE)

Application

EP 06828982 A 20061109

Priority

- EP 2006010750 W 20061109
- DE 102005053851 A 20051109
- DE 102005054294 A 20051111

Abstract (en)

[origin: WO2007054306A1] The invention relates to a soldering method for joining different basic metallic materials at least at one soldering point with the aid of solder which is fused on using thermal energy. In order to simplify the production of heat exchangers, at least some of the thermal energy required for fusing on the solder at the soldering point is generated by means of an exothermal reaction to which a reactive substance contributes that is supplied at the soldering point. The invention also relates to a heat exchanger which can be produced especially according to said method.

IPC 8 full level

B23K 1/00 (2006.01); **B23K 1/008** (2006.01); **B23K 1/20** (2006.01); **B23K 35/28** (2006.01); **B23K 35/34** (2006.01); **F28F 21/08** (2006.01)

CPC (source: EP)

B23K 1/0006 (2013.01); **B23K 1/0012** (2013.01); **B23K 1/008** (2013.01); **B23K 1/20** (2013.01); **F28F 21/084** (2013.01); **H05K 3/3494** (2013.01); **B23K 2101/14** (2018.07); **F28F 2275/06** (2013.01); **H05K 3/3457** (2013.01); **H05K 2203/1163** (2013.01)

Citation (search report)

See references of WO 2007054306A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2007054306 A1 20070518; EP 1951468 A1 20080806

DOCDB simple family (application)

EP 2006010750 W 20061109; EP 06828982 A 20061109